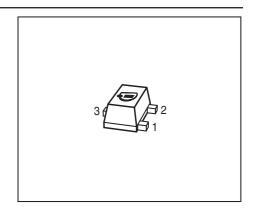


Low Noise Silicon Bipolar RF Transistor

- For low noise, high-gain amplifiers up to 2 GHz
- For linear broadband amplifiers
- f_T = 8 GHz, NF_{min} = 1 dB at 900 MHz
- Pb-free (RoHS compliant) and halogen-free product
- Qualification report according to AEC-Q101 available







ESD (Electrostatic discharge) sensitive device, observe handling precaution!

Туре	Marking	Pin Configuration			Package
BFR193F	RCs	1 = B	2 = E	3 = C	TSFP-3

Maximum Ratings at T_A = 25 °C, unless otherwise specified

Parameter	Symbol	Value	Unit
Collector-emitter voltage	V_{CEO}	12	V
Collector-emitter voltage	V_{CES}	20	
Collector-base voltage	V_{CBO}	20	
Emitter-base voltage	V_{EBO}	2	
Collector current	I _C	80	mA
Base current	I _B	10	
Total power dissipation ¹⁾	P _{tot}	580	mW
<i>T</i> _S ≤ 72°C			
Junction temperature	TJ	150	°C
Storage temperature	T_{Stq}	-55 150	

Thermal Resistance

Parameter	Symbol	Value	Unit
Junction - soldering point ²⁾	R _{thJS}	135	K/W

 $^{{}^{1}}T_{\mbox{S}}$ is measured on the collector lead at the soldering point to the pcb

 $^{^2}$ For the definition of $R_{ ext{thJS}}$ please refer to Application Note AN077 (Thermal Resistance Calculation)



Electrical Characteristics at T_A = 25 °C, unless otherwise specified

Parameter	Symbol	l Values			Unit	
		min.	typ.	max.		
DC Characteristics						
Collector-emitter breakdown voltage	V _{(BR)CEO}	12	-	-	V	
$I_{\rm C} = 1 \text{ mA}, I_{\rm B} = 0$, ,					
Collector-emitter cutoff current	I _{CES}	-	-	100	μΑ	
$V_{CE} = 20 \text{ V}, V_{BE} = 0$						
Collector-base cutoff current	I _{CBO}	-	-	100	nA	
$V_{\rm CB} = 10 \text{ V}, I_{\rm E} = 0$						
Emitter-base cutoff current	I _{EBO}	-	-	1	μΑ	
$V_{\rm EB} = 1 \text{ V}, I_{\rm C} = 0$						
DC current gain	h _{FE}	70	100	140	-	
$I_{\rm C}$ = 30 mA, $V_{\rm CE}$ = 8 V, pulse measured						



Electrical Characteristics at T_A = 25 °C, unless otherwise specified

Electrical Characteristics at $T_A = 25$ °C, unless Parameter	Symbol	Values			Unit
		min.	typ.	max.	
AC Characteristics (verified by random samplin	g)				
Transition frequency	f _T	6	8	-	GHz
$I_{\rm C}$ = 50 mA, $V_{\rm CE}$ = 8 V, f = 500 MHz					
Collector-base capacitance	C _{cb}	-	0.63	1	pF
V_{CB} = 10 V, f = 1 MHz, V_{BE} = 0, emitter grounded					
Collector emitter capacitance	C_{ce}	-	0.25	-	
V_{CE} = 10 V, f = 1 MHz, V_{BE} = 0, base grounded					
Emitter-base capacitance	C_{eb}	-	2.25	-	
$V_{\text{EB}} = 0.5 \text{ V}, f = 1 \text{ MHz}, V_{\text{CB}} = 0$,					
collector grounded					
Minimum noise figure	NF _{min}				dB
$I_{\rm C}$ = 10 mA, $V_{\rm CE}$ = 8 V, $Z_{\rm S}$ = $Z_{\rm Sopt}$,					
f = 900 MHz		_	1	_	
f = 1.8 GHz		-	1.6	_	
Power gain, maximum stable ¹⁾	G _{ms}	-	12.5	-	dB
$I_{\rm C}$ = 30 mA, $V_{\rm CE}$ = 8 V, $Z_{\rm S}$ = $Z_{\rm Sopt}$,					
$Z_{L} = Z_{Lopt}$, $f = 900 \text{ MHz}$					
Power gain, maximum available ¹⁾	G _{ma}	-	19	-	dB
$I_{\rm C}$ = 30 mA, $V_{\rm CE}$ = 8 V, $Z_{\rm S}$ = $Z_{\rm Sopt}$,					
$Z_{L} = Z_{Lopt}$, $f = 1.8 \text{ GHz}$					
Transducer gain	S _{21e} ²				dB
$I_{\rm C}$ = 30 mA, $V_{\rm CE}$ = 8 V, $Z_{\rm S}$ = $Z_{\rm L}$ =50 Ω , f = 900 MHz		_	14.5	-	
f = 1.8 GHz		-	8.5	_	
Third order intercept point at output ²⁾	IP ₃	-	29	-	dBm
$V_{CE} = 8 \text{ V}, I_{C} = 30 \text{ mA}, f = 900 \text{ MHz},$					
$Z_{\rm S} = Z_{\rm L} = 50 \ \Omega$					
1dB compression point at output ³⁾	P _{-1dB}	-	14.5	-	1
$I_{\rm C}$ = 30 mA, $V_{\rm CF}$ = 8 V, $Z_{\rm S}$ = $Z_{\rm L}$ = 50 Ω ,	.35				
f = 900 MHz					

 $^{{}^{1}}G_{\text{ma}} = |S_{21} / S_{12}| (k-(k^{2}-1)^{1/2}), \ G_{\text{ms}} = |S_{21} / S_{12}|$

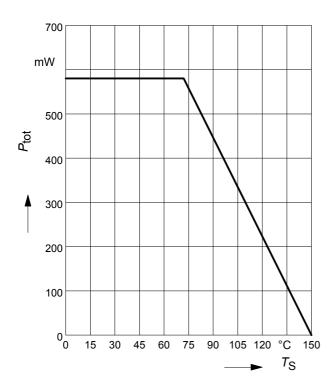
²IP3 value depends on termination of all intermodulation frequency components.

Termination used for this measurement is 50Ω from 0.1 MHz to 6 GHz

³DC current at no input power



Total power dissipation $P_{tot} = f(T_S)$

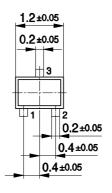


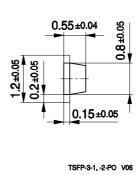
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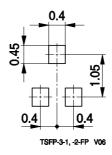
Package Outline



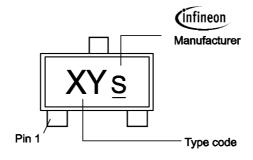




Foot Print

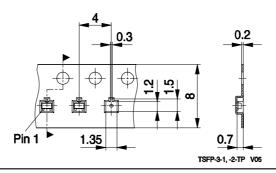


Marking Layout (Example)



Standard Packing

Reel Ø 180 mm = 3.000 Pieces/Reel Reel Ø 330 mm = 10.000 Pieces/Reel



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Edition 2009-11-16

Published by Infineon Technologies AG 81726 Munich, Germany

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